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Date: 13 Apr 2018

CORRIGENDUM – 2

1. It is notified to all concerned that with reference to IITH Tender No. **IITH/5(8)/SVANJARI/2017/T222** dated **16 Mar 2018** for **supply, installation and commissioning of "DRIE and ICPRie"**, the following changes are made w.r.t. the Tender: -

(a) **Revised Specifications** enclosed as per **Annexure -1 (12 pages)**.

2. If any bidder has already submitted the bid prior to issue of this corrigendum, it is required to re-submit the bid before the revised Due Date & Time considering changes in the specifications of the Tender as per this corrigendum.

3. All other Terms & Conditions of Tender remain completely unchanged.

Yours faithfully,

(V.VENKAT RAO)
Joint Registrar
IIT Hyderabad

Annexure -1

Original Tender No. IITH/5(8)/SVANJARI/2017/T222 dated 16 Mar 2018

Details	Original Specification	Modified Specification after Pre-Bid
P11 2.1.1f	Suitable gauges, calibrated as per CE/SEMI/equivalent international traceable standard must be provided for monitoring vacuum in process chamber, load-lock and providing feedback for controlling process pressure in the chamber. Pressure gauges to monitor the lines between chamber and turbo pump, and turbo pump to backing pump must be provided to ensure best possible vacuum performance.	Suitable gauges, calibrated as per CE/SEMI/equivalent international traceable standard must be provided for monitoring vacuum in process chamber, load-lock and providing feedback for controlling process pressure in the chamber.
P12 2.1.2a	The chamber should be machined from a single metal block with suitable ports for Plasma source, pumping unit, load-lock, viewing and end point detection attachment. The view ports should have UV and RF protective coatings.	The chamber should be machined from a single metal block with suitable ports for Plasma source, pumping unit, load-lock, viewing and end point detection attachment. The view ports should have UV protecting coating. In addition RF coatings are preferable
P12, 2.1.2d	Magnetically Levitated/suitable Turbo-pump with a pumping speed of 2000 l/s.	Magnetically Levitated/suitable Turbo-pump to achieve an ultimate vacuum of 5×10^{-7} torr.
P12, 2.1.2e	Suitable pumping flange (with dia ≥ 250 mm) with effective pumping speed	Suitable pumping flange (with dia ≥ 200 mm) with effective pumping speed
P12, 2.1.2f	Turbo should be off tee below the chamber to provide axially symmetric pumping, whilst avoiding accidental damage by chamber debris. Pump-down pipe of suitable diameter (250 mm recommended) for high throughput pumping and APC with equally large internal diameter. System should have automatic pressure control with a pendulum valve response of <1 second	A suitable turbo that can guarantee the chamber pressure requirements specified must be included. The ultimate chamber pressure must be better than 5×10^{-7} Torr. Suitable protection measures for preventing the wafer pieces from being sucked into the turbo must be provided.
P12, 2.1.2g	Dry backing pump 100 cu.m/ hour rating with N ₂ purge standby	Dry backing pump rating of 1300 l/min or more with N ₂ purge standby
P12 2.1.3a	The system/cluster should have an automatic load lock and the pumping speed of load lock pumping system should achieve 30 mT in less than 2 min.	Null/Void. This specification is removed.
P12 2.1.3b	The loading mechanism should be software	The loading mechanism should be

